

## Editorial

**Cite this article:** Lewark UJ (2025) EuMIC 2023 Special Issue. *International Journal of Microwave and Wireless Technologies*, 1. <https://doi.org/10.1017/S1759078725101712>

Received: 24 April 2025

Revised: 15 May 2025

Accepted: 16 May 2025

**Corresponding author:**

Ulrich Johannes Lewark;

Email: [ulrich.lewark@imst.de](mailto:ulrich.lewark@imst.de)

This special issue to the 18th European Microwave Integrated Circuits (EuMIC 2023) is one of the trilogy of special issues to the European Microwave Week (EuMW 2023), whose 26th edition was held from the 17th to 22nd of September 2023 in Berlin, Germany. As one of the three sister conferences comprising EuMW, the European Integrated Circuits Conference is the premier European technical conference for RF & microwave microelectronics.

The 18th European Integrated Circuits (EuMIC 2023) was held from the 18th to 19th of September 2023 in Berlin, Germany, as part of European Microwave Week 2023, jointly organized by the GAAS® Association and EuMA since 2006.

With an impressive number of over 150 paper submissions in 2023, we were pleased to see a continuously high interest in the European microwave integrated circuit community. EuMIC 2023 covered a broad range of microwave, mm-wave, terahertz, and related topics, from materials and technologies to integrated circuits and applications.

The authors of the top-rated conference contributions have been invited to submit an extended manuscript to the special issue of the *International Journal of Microwave and Wireless Technologies* (IJMWT). All manuscripts received went through an additional peer review process. As associate editor of this EuMIC 2023 special issue, I would like to warmly thank all authors for their excellent contributions and the reviewers for the professional and timely preparation of their reviews.

To conclude, we would like to wish you a pleasant reading of this EuMIC 2023 special issue and invite you to submit your research results to the IJMWT!



**Ulrich Johannes Lewark** was born in Kaiserslautern, Germany, in 1986. He received the Dipl.-Ing. (M.S.E.E) and Dr.-Ing. (Ph.D.E.E.) degrees from the Karlsruhe Institute of Technology (KIT), Karlsruhe, Germany, in 2010 and 2015, respectively. From 2010 to 2015, he was a Research and Teaching Assistant with the Institut für Hochfrequenztechnik und Elektronik (IHE), KIT, where he was involved in the development of monolithic integrated circuits for radar imaging and broadband communication systems up to sub-millimeter wave range. Since 2015, he is with the IMST GmbH, Kamp-Lintfort, Germany, and since 2017 managing a design team for GaAs, GaN, and SiGe MMICs at IMST. The team is covering specialized MMICs for communication and space applications from LNA over PA to complex integrated ICs such as frequency synthesizers and beam former ICs up to 140 GHz.